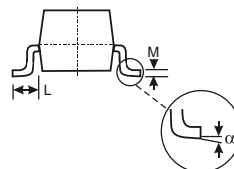
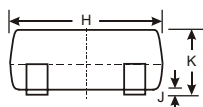
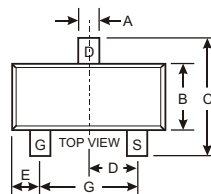


### Features

- Super high density cell design for extremely low  $R_{DS(ON)}$ .
- Exceptional on-resistance and maximum DC current capability.
- We declare that the material of product compliance with RoHS requirements.



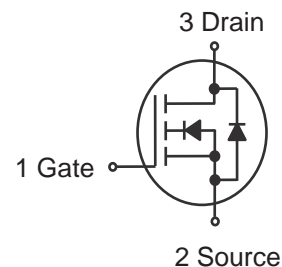
SOT-23		
Dim	Min	Max
A	0.37	0.51
B	1.20	1.40
C	2.30	2.50
D	0.89	1.03
E	0.45	0.60
G	1.78	2.05
H	2.80	3.00
J	0.013	0.10
K	0.903	1.10
L	0.45	0.61
M	0.085	0.180
$\alpha$	0°	8°
All Dimensions in mm		

### APPLICATIONS

- TrenchFET Power MOSFET.
- Load Switch for Portable Devices.
- DC/DC Converter.
- Marking Code:S4 OR 2304.

### Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	3.6	A
Pulsed Drain Current	$I_{DM}$	15	
Continuous Source-Drain Diode Current	$I_S$	0.9	
Maximum Power Dissipation	$P_D$	0.35	W
Thermal Resistance from Junction to Ambient ( $t \leq 5s$ )	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Storage Temperature	$T_J$	150	$^\circ\text{C}$
Junction Temperature	$T_{STG}$	-55 ~ +150	



### Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

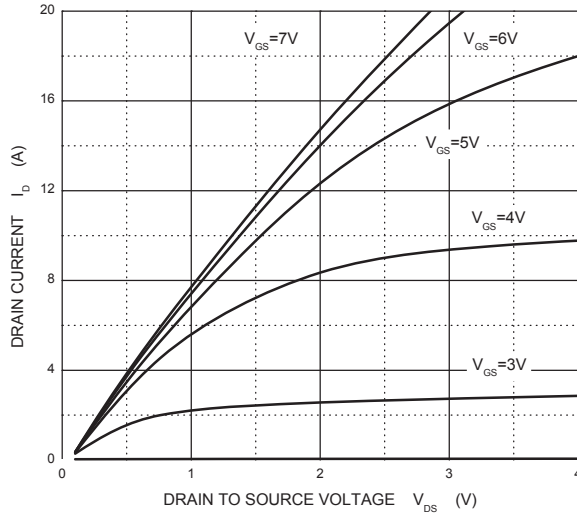
Parameter	Symbol	Test condition	Min	Typ	Max	Units
Static						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	30			V
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.6	2.3	
Gate-body leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V			1	μA
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.6A		0.027	0.033	Ω
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3.0A		0.042	0.051	
Forward transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> =4.5V, I <sub>D</sub> =3.0A	2.5			S
Dynamic <sup>b</sup>						
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> =15V,V <sub>GS</sub> =10V,I <sub>D</sub> =3.6A		4.5	6	nC
		V <sub>DS</sub> =15V,V <sub>GS</sub> =4.5V,I <sub>D</sub> =3.6A		2.1	3	
Gate-source charge	Q <sub>gs</sub>			0.85		
Gate-drain charge	Q <sub>gd</sub>			0.65		
Gate resistance	R <sub>g</sub>	f =1.0MHz	0.8	4.4	8	Ω
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V,f =1MHz		235		pF
Output capacitance	C <sub>oss</sub>			45		
Reverse transfer capacitance	C <sub>rss</sub>			17		
Turn-on delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, R <sub>L</sub> =5.6Ω, I <sub>D</sub> ≈3.0A, V <sub>GEN</sub> =4.5V,R <sub>g</sub> =1Ω		12	2	ns
Rise time	t <sub>r</sub>			50	7	
Turn-off delay time	t <sub>d(off)</sub>			12	2	
Fall time	t <sub>f</sub>			22	3	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, R <sub>L</sub> =5.6Ω, I <sub>D</sub> ≈3.0A, V <sub>GEN</sub> =10V,R <sub>g</sub> =1Ω		5	10	
Rise time	t <sub>r</sub>			12	2	
Turn-off delay time	t <sub>d(off)</sub>			10	1	
Fall time	t <sub>f</sub>			5	10	
Drain-source body diode characteristics						
Continuous source-drain diode current	I <sub>S</sub>	T <sub>C</sub> =25°C			1.4	A
Pulse diode forward current	I <sub>SM</sub>				15	A
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> =-2.7A,V <sub>GS</sub> =0V		0.8	1.2	V

#### Notes :

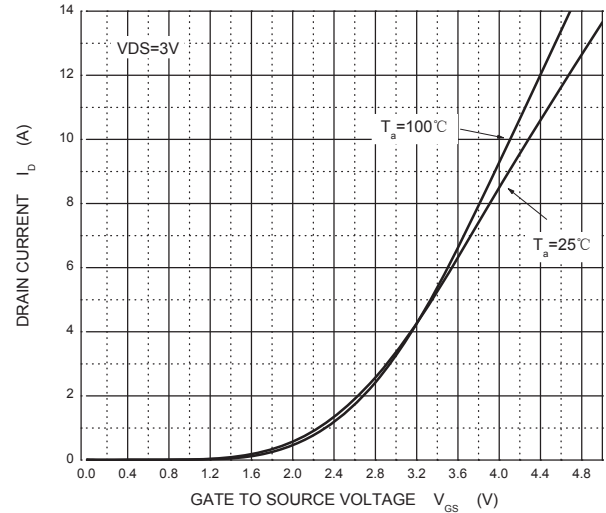
- a. Puls Test : Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.

### TYPICAL TRANSIENT CHARACTERISTICS

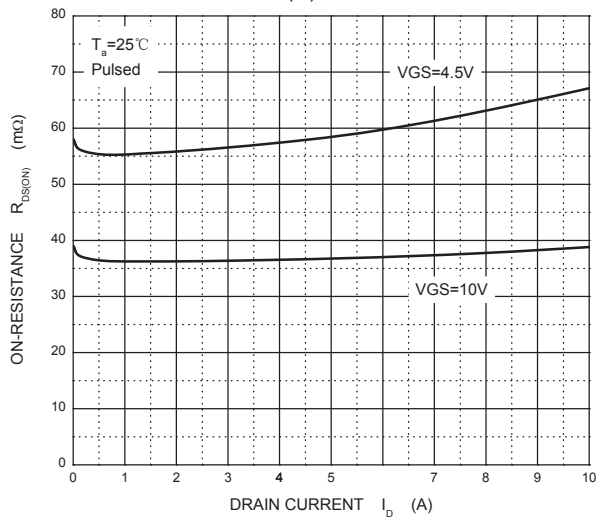
Output Characteristics



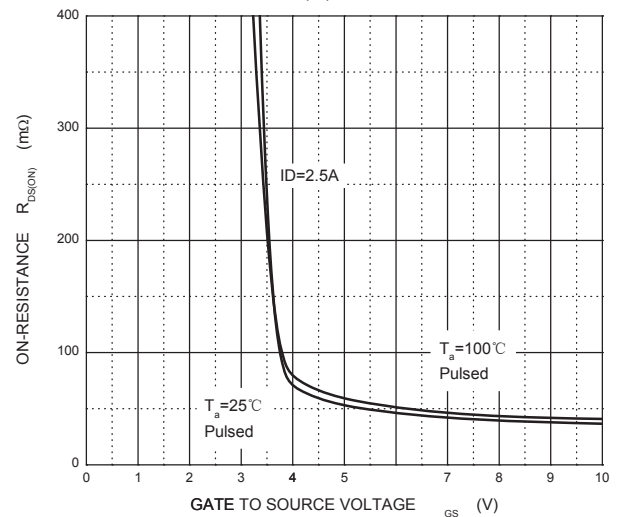
Transfer Characteristics



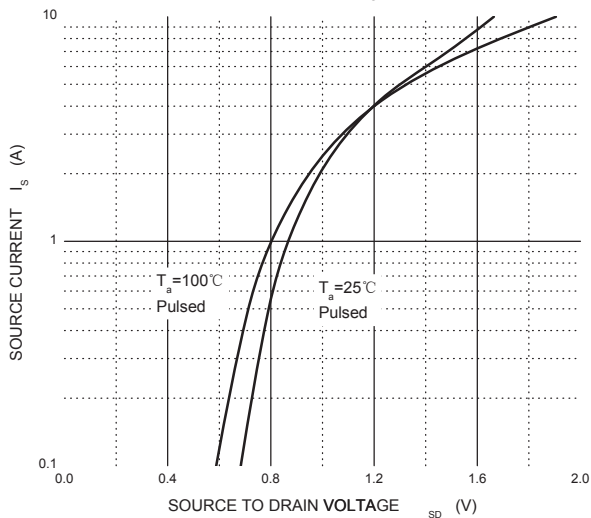
$R_{DS(ON)}$  —  $I_D$



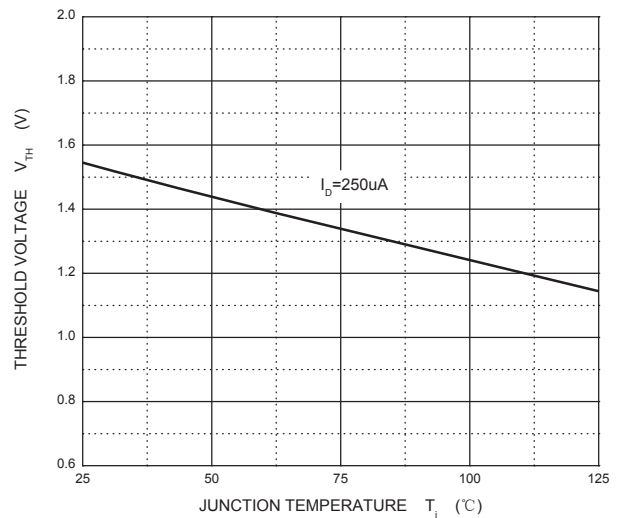
$R_{DS(ON)}$  —  $V_{GS}$



$I_S$  —  $V_{SD}$



Threshold Voltage



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### IMPORTANT NOTICE

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